

September 18, 2018

Press Release – MacDermid Enthone Advanced Electronics Solutions to Present at the 2018 IMAPS International Conference

Waterbury, CT., September 18, 2018 – MacDermid Enthone Electronics Solutions (MEES), a MacDermid Performance Solutions business, will present at the 51st International Symposium on Microelectronics - IMAPS 2018. The conference will be held October 8-11, at the Pasadena Convention Center, Pasadena, CA, USA.

Eric Gongora, General Manager Americas and Europe and Strategic Marketing Director of Wafer Level Packaging, MacDermid Enthone Advanced Electronics Solutions (AES), will address the continuous challenges faced in developing advanced packaging electroplating chemistries required to meet the performance, operational efficiency and time to market demands driven by the need for higher level of integration and heterogeneous solutions. Eric will present his paper; "Customization of Chemistry Continues", on Wednesday, October 10 Session 118 at 11:00am. Eric will also serve as Session Chair for the Wafer-level Fan Out segment of the conference.

AES, a segment within the MEES business, is a global leader in high performance semiconductor chemistries and assembly materials. AES engages directly with OEMs, IDMs, wafer foundries, OSATs and tool suppliers to collaboratively develop solutions that meet the fast paced semiconductor market demands.

About MacDermid Enthone Electronics Solutions: MacDermid Enthone Electronics Solutions researches, formulates and delivers specialty chemistries used in the world's leading electronics. Our products and technical support provide solutions for the most complicated, micro scale circuitry challenges. From wireless devices to automotive and military electronics – in everything you see, and in many things you don't – MacDermid Enthone is there. Visit us at: macdermidenthone.com/electronics.

For more information on our latest advances in electronics, contact us at infoelectronics@macdermidenthone.com.

